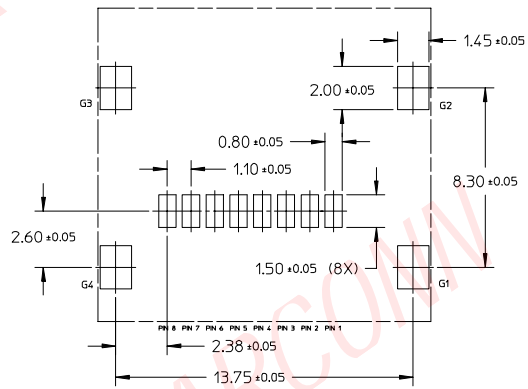
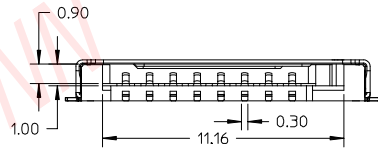
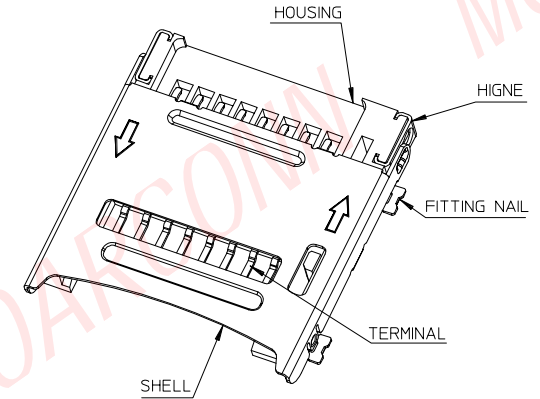
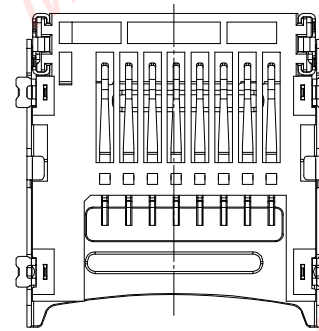
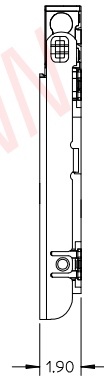
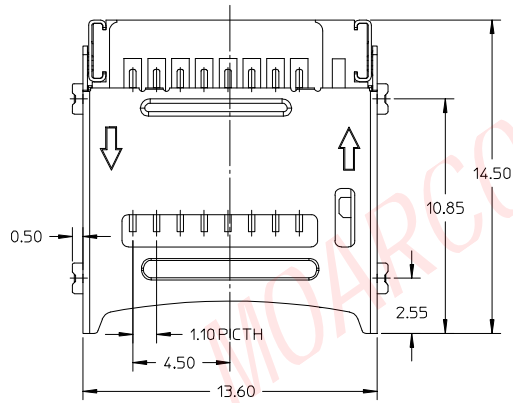


All materials, plating and process meet HF requirements.



RECOMMENDED PCB LAYOUT

IN CASE OF STENCIL THICKNESS: 0.12MM  
OPEN RATIO IS 100%.  
IN CASE OF STENCIL THICKNESS : 0.1MM  
OPEN RATIO IS 100% MINIMUM.  
(0.08MM STENCIL THICKNESS CAN NOT BE RECOMMENDED)

G4	GND
G3	GND
G2	GND
G1	GND
PIN8	DAT1
PIN7	DAT0
PIN6	VSS
PIN5	CLK
PIN4	VDD
PIN3	CMD
PIN2	CD/DAT3
PIN1	DAT2
PIN NUMBER	PIN NAME

NOTES:

- MATERIAL:
  - 1-1 TERMINAL, FITTING NAIL, HIGNE : COPPER ALLOY
  - 1-2 SHELL : STAINLESS STEEL
  - 1-3 HOUSING : LCP, UL 94-V0, BLACK
- FINISH:
  - 2-1 TERMINAL : OVERALL NICKEL UNDERPLATED, GOLD PLATING ON CONTACT AREA  
TIN PLATING ON SOLDER TAIL
  - 2-2 FITTING NAIL : OVERALL NICKEL UNDERPLATED, TIN PLATED ON SOLDER AREA
  - 2-3 HIGNE : OVERALL NICKEL PLATING
- MECHANICAL SPECIFICATION:
  - DURABILITY MATED 5,000 TIMES AND STILL MEET ELECTRICAL CHARACTERISTICS
- ELECTRICAL SPECIFICATION:
  - 4-1 RATED CURRENT (PER CONTACT) : 0.5AMPS MAX AND  
TEMPERATURE RISE SHOULD BE 30°C MAX
  - 4-2 INSULATION RESISTANCE(I.R):100 MEGOHMS MIN.
  - 4-3 DIELECTRIC WITHSTANDING VOLTAGE : N/A
  - 4-4 CONTACT RESISTANCE: 100 MILLIOHMS MAX
- COMPLIANT TO ROHS DIRECTIVE 2002/95/EC  
AND ELV 2000/53/EC.

**MOARCONN**<sup>®</sup>  
More Connections Smart Future

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DIMENSIONS INIT: mm	
UNLESS OTHERWISE SPECIFIABLE	
DIMENSION	TOLERANCE
X.X: ±	0.10
X.XX: ±	0.05
X.XXX: ±	0.02
ANGULAR: ±	1°

PRODUCT NAME : Micro SD H1.90 SMT Card	DRAWING: Zhangli	DATE: 2025.1.4
PRODUCT NO. : MC190-T1230-01-W	CHECK: /	DATE: /
DRAWING NO. : D-TF190-T1230-01-W	APPROVED:	DATE:
SCALE: 1:1	DWG ID: P D	REV.: X0
		PAGE: 1 OF 1

X0	-----	NEW RELEASE	Zhangli	2025.1.4
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1		2	3	4

A

B

C

D

E

F